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PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Pei-Cheng Hsu	04/23/2012
Chih-Tsung Shih	04/23/2012
Chia-Jen Chen	04/23/2012
Tsiao-Chen Wu	04/23/2012
Shinn-Sheng Yu	04/23/2012
Hsin-Chang Lee	04/23/2012
Anthony Yen	04/23/2012

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13451705

OP $40.00 13451705

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.2108/2011-1630
NAME OF SUBMITTER:	David M. O'Dell
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Docket No.: 2011-1630 / 24061.2108
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Pei-Cheng Hsu of No. 23, Alley 12, Lane 63, Wu-Cheng Street
Taipei, Taiwan, R.O.C.

(2) Chih-Tsung Shih of 7F, No. 2, Nanzhong Street, North District
Hsinchu City 300, Taiwan, R.O.C.

(3) Chia-Jen Chen of No. 19-3, Sanchong 1st Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

(4) Tsiao-Chen Wu of No. 19, Lane 180, Dalin Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

(5) Shinn-Sheng Yu of 4F-2, No. 16, Lane 634, Nanda Road
Hsinchu, Taiwan, R.O.C

(6) Hsin-Chang Lee of No. 121, Wen-Hua Road, Wen-Shan Li
Hsin-Pu Zhen, Hsin-Chu Xian, Taiwan, R.O.C.

(7) Anthony Yen of 17F, 296-5, Guangming 6th Road, E., Sec. 1
Zhubei City Hsinchu City 302, Taiwan, R.O.C.

have invented certain improvements in

REFLECTIVE MASK AND METHOD OF MAKING SAME

for which we have executed an application for Letters Patent of the United States of America on **April 20, 2012**, as U.S. Serial No.**13/451,705**; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Pei-Cheng Hsu

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Dated: 2012, 4, 23

Pei-Cheng Hsu
Inventor Signature

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Dated: 2012 . 4 . 23

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Dated: 2012 . 4 . 23

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Dated: Hsin-Chang Lee

2014 . 4 . 23
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Docket No.: 2011-1630 / 24061.2108
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Dated: 4/23/2012

Inventor Signature
